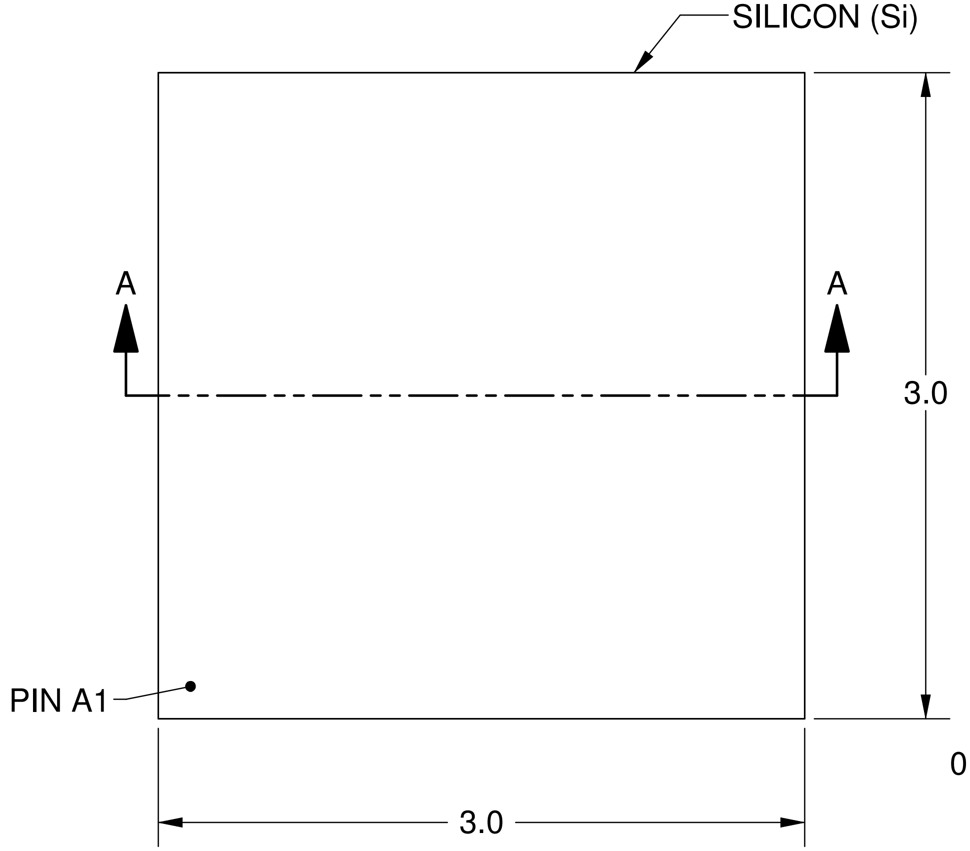
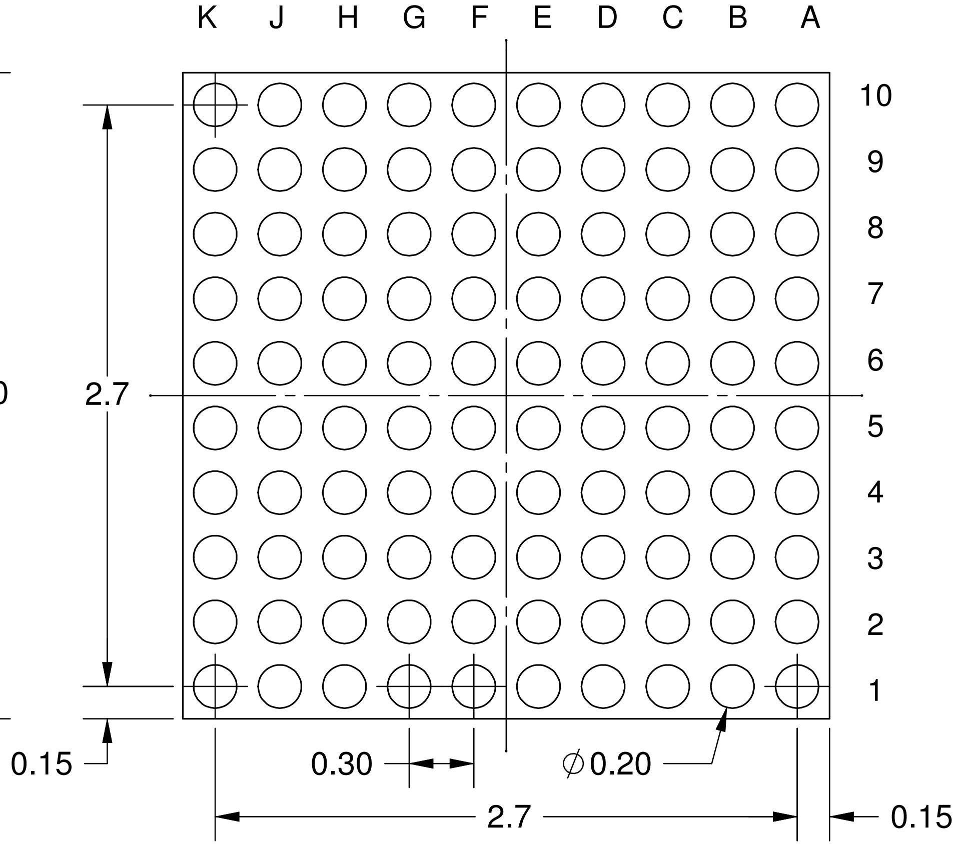
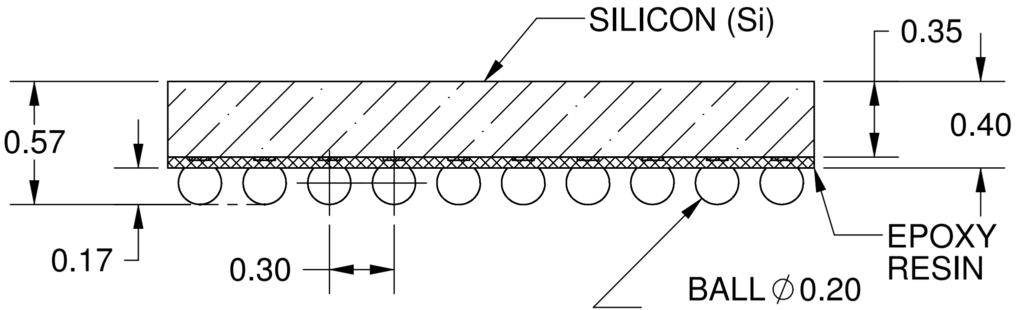
TOP VIEW



BALL VIEW





SECTION A-A

Notes: (Unless Otherwise Specified).
1) ALL DIMENSIONS ARE IN MM.
2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
3) BALL DIAMETER (BEFORE REFLOW): 0.20mm.
4) NON-SOLDER MASK DEFINED PAD.
5) PAD Cu DIAMETER: 0.15mm.
6) SUBSTRATE MATERIAL: Si (SILICON).
7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	**BALL ALLOY**	**Pb-FREE**	**RoHS**	**Si DIE**
WLP100T.3C-DC108D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP100T.3C1-DC108D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

TOLERANCE UNLESS NOTED		APPROVALS	DATE
X.X	+/- 0.3		
X.XX	+/- 0.03	DRAWN J. Hines	12/29/2010
X.XXX	+/- 0.003		
ANGLES	+/- 0.5°	ENG	
ALL DIMENSIONS IN ☐ INCHES ☒ MILLIMETERS		MFG	
THIRD ANGLE PROJECTION		QA	
		CUST	
		REVISED	

TopLine®

TITLE WLP100T.3C-DC108D
100-BALL P=0.3mm (TEG0306)

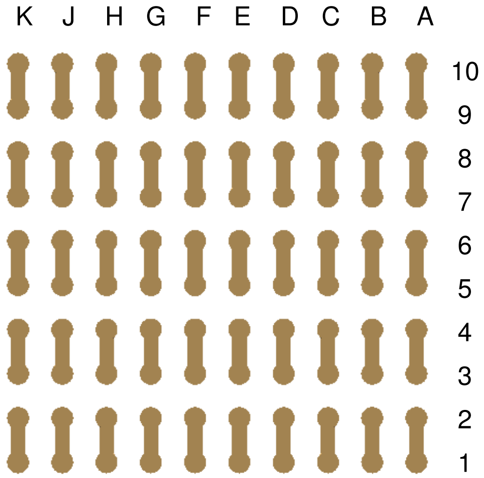
SCALE	SIZE	DRAWING NO.	REV
28.5:1	A	531082	A

DO NOT SCALE DRAWING

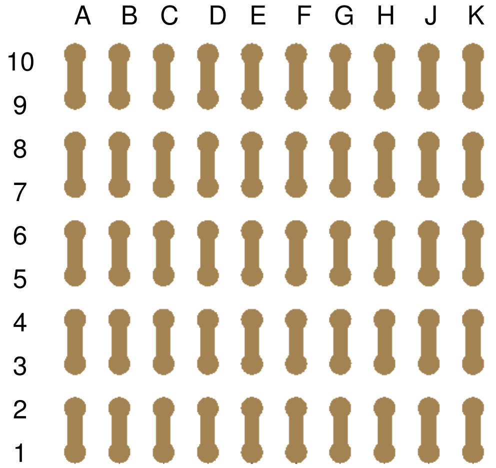
SHEET 1 OF 2

DAISY CHAIN PATTERN

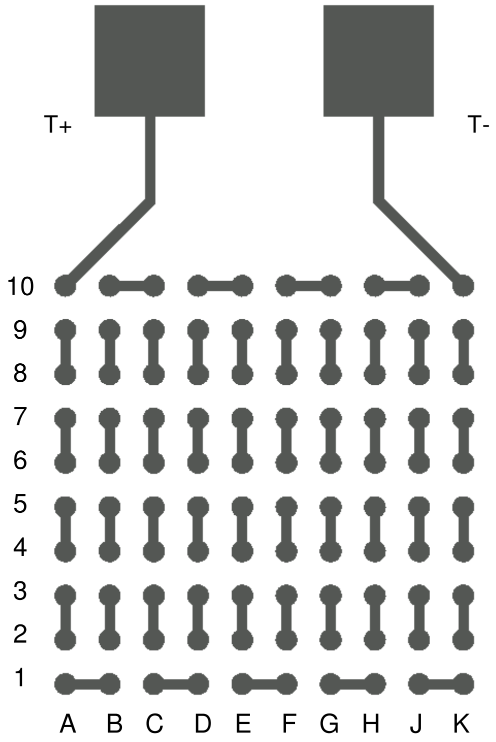
BALL VIEW



BOTTOM SIDE
(TOP X-RAY VIEW)

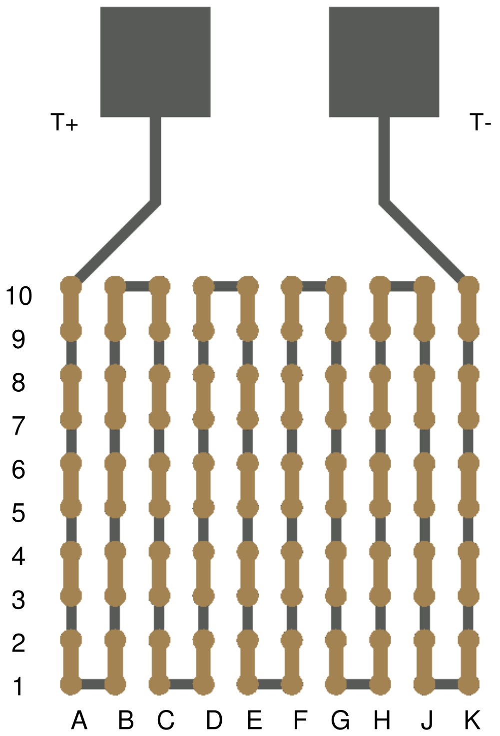


TOP VIEW



TEST VEHICLE BOARD

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:
1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2) PCB Cu BALL PAD DIAMETER 0.15mm (5.9mil).
3) PCB DAISY CHAIN TRACING LINE WIDTH 0.07mm (3mil).

TopLine®

TITLE WLP100T.3C-DC108D 100-BALL P=0.3mm (TEG0306)			
SCALE 19.5:1	SIZE A	DRAWING NO. 531082	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	